# Nch 45V 3A Middle Power MOSFET

$V_{DSS}$	45V
R <sub>DS(on)</sub> (Max.)	67mΩ
I <sub>D</sub>	±3A
P <sub>D</sub>	1.0W

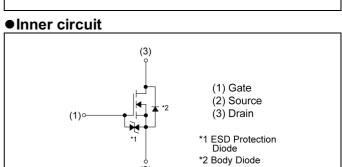
# Features

- 1) Low on-resistance
- 2) Built-in G-S protection diode
- 3) Small surface mount package(TSMT3)

Outline SOT-346T

SC-96

TSMT3



Packaging specifications

	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TL
	Marking	PV

# Application

Switching

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	45	V
Continuous drain current	I <sub>D</sub>	±3	Α
Pulsed drain current	I <sub>DP</sub> *1	±12	Α
Gate - Source voltage	V <sub>GSS</sub>	±12	V
Device discinstice	P <sub>D</sub> *2	1.0	W
Power dissipation	P <sub>D</sub> *3	0.76	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

### ●Thermal resistance

Deremeter	Symbol	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registance junction, ambient	R <sub>thJA</sub> *2	-	-	125	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *3	-	-	165	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	45	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	46.8	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 45V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate - Source leakage current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	±10	μA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_{D} = 1mA$	0.5	-	1.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3.9	-	mV/°C
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A	-	48	67	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	$V_{GS} = 4V$ , $I_D = 3A$	-	53	74	mΩ
		$V_{GS} = 2.5V, I_D = 3A$	-	68	95	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	6.7	1	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 10V, I <sub>D</sub> = 3A	2.8	-	-	S

<sup>\*1</sup> Pw $\leq$ 10 $\mu$ s, Duty cycle $\leq$ 1%

<sup>\*2</sup> Mounted on a ceramic board (30x30x0.8mm)

<sup>\*3</sup> Mounted on a FR4 (25x25x0.8mm)

<sup>\*4</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Cymahal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	510	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 10V	-	110	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	55	-		
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 25V, V_{GS} = 4.5V$	-	12	-		
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 1.5A	-	19	-		
Turn - off delay time	t <sub>d(off)</sub> *4	R <sub>L</sub> ≃ 16.6Ω	-	34	-	ns	
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	26	-		

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,					
Parameter	Cymbal	Conditions	Values			Unit	
raiametei	Symbol Conditions		Min.	Тур.	Max.	Offic	
Total gate charge	Qg*4	V <sub>DD</sub> ≃ 25V.	-	6.2	-		
Gate - Source charge	Q <sub>gs</sub> *4	$V_{DD} \approx 25V$ , $I_D = 3A$ , $V_{GS} = 4.5V$	-	1.6	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *4	$V_{GS} = 4.5V$	-	1.4	-		

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol Conditions		Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	0.8	Α
Pulse forward current	I <sub>SP</sub> *1	T <sub>a</sub> = 25°C	-	-	12	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 3A	-	-	1.2	V

Fig.1 Power Dissipation Derating Curve

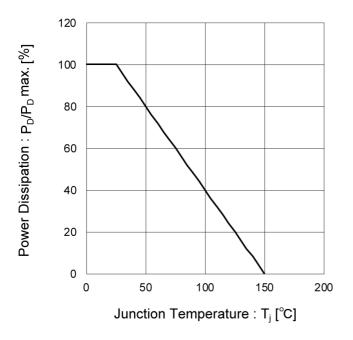
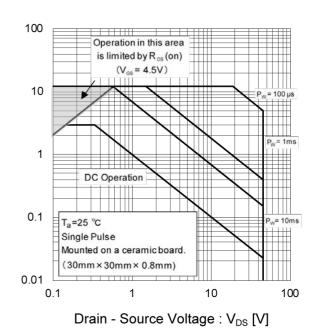


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

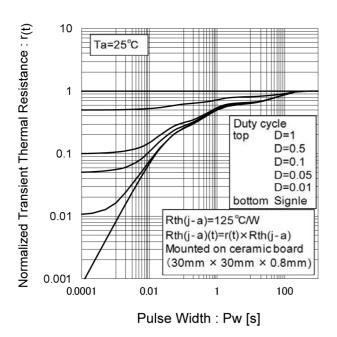
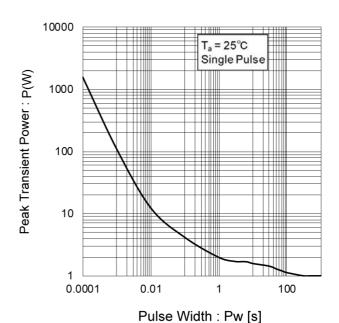


Fig.4 Single Pulse Maximum Power dissipation



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Fig.5 Typical Output Characteristics(I)

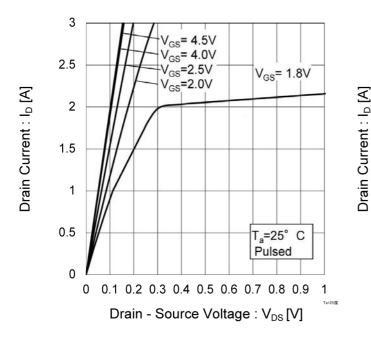


Fig.6 Typical Output Characteristics(II)

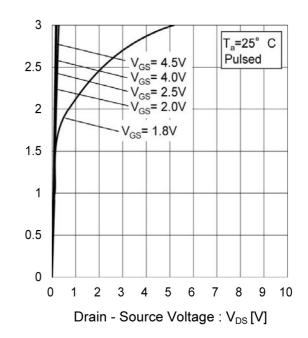


Fig.7 Breakdown Voltage vs.

Junction Temperature

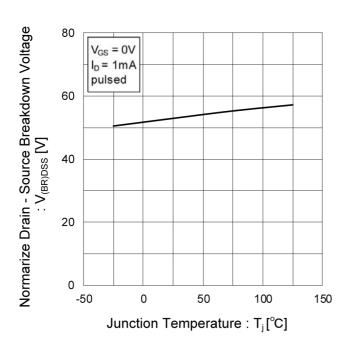
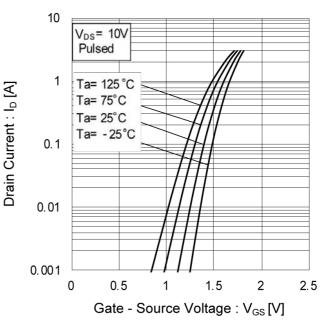


Fig.8 Typical Transfer Characteristics



Gate Threshold Voltage :  $V_{GS(th)}[V]$ 

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

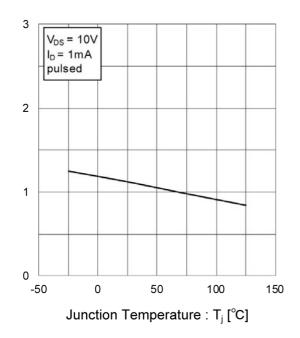


Fig.10 Forward Transfer Admittance vs.
Drain Current

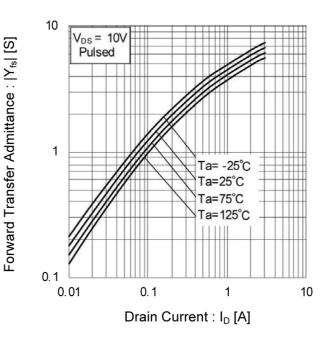


Fig.11 Drain Current Derating Curve

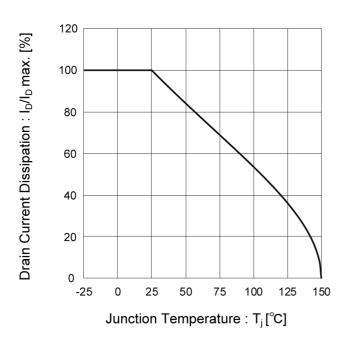
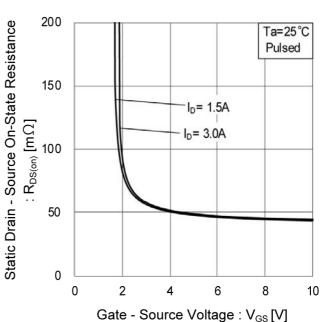


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



RTR030N05

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

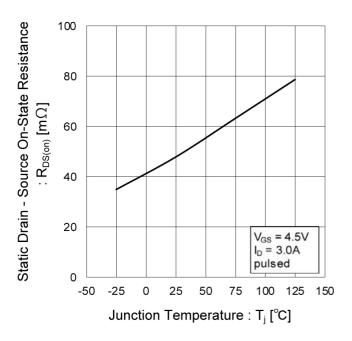


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

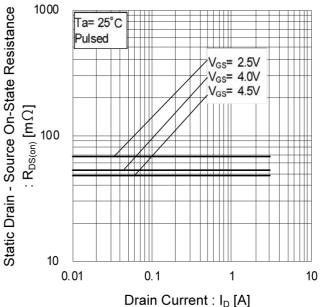


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

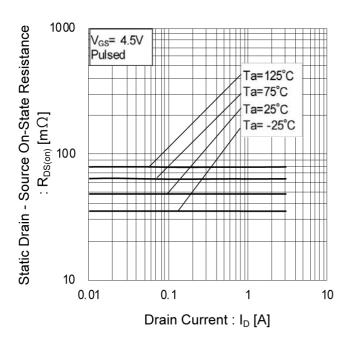


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

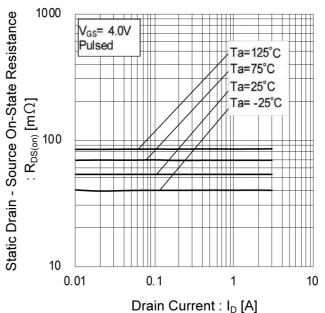


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

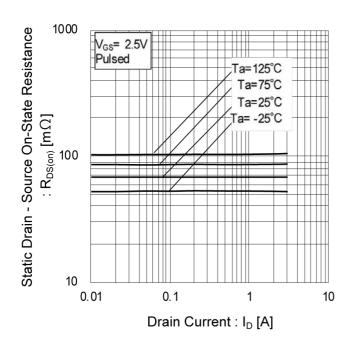


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

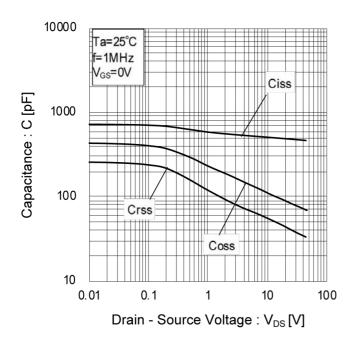


Fig.19 Switching Characteristics

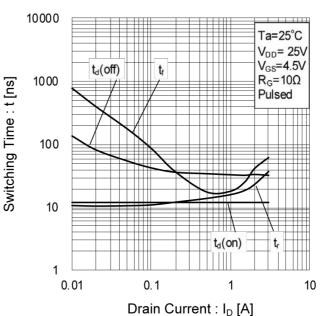


Fig.20 Dynamic Input Characteristics

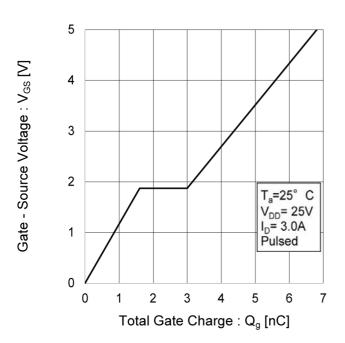
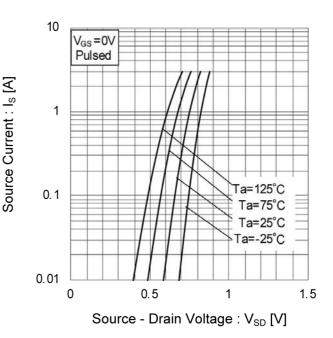


Fig.21 Source Current vs.

Source Drain Voltage



### Measurement circuits

Fig. 1-1 SWITCHING TIME MEASUREMENT CIRCUIT

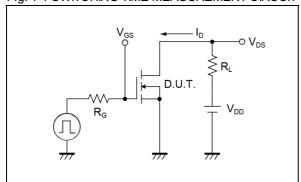


Fig. 2-1 GATE CHARGE MEASUREMENT CIRCUIT

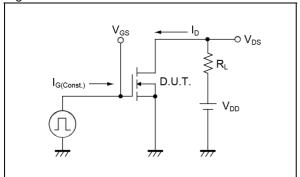


Fig. 1-2 SWITCHING WAVEFORMS

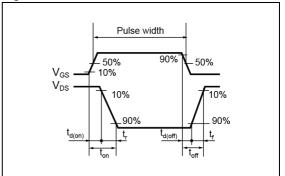
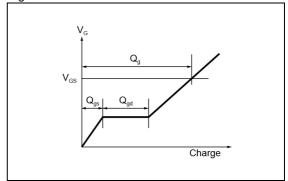
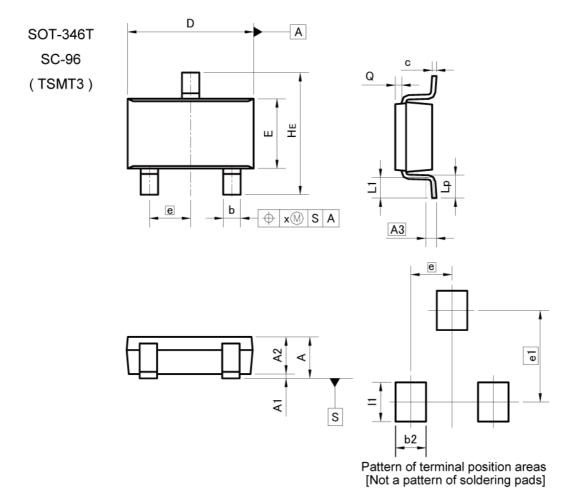


Fig. 2-2 GATE CHARGE WAVEFORM



### Dimensions



DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	=3	1.00	<del>-</del>	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
x	75%	0.20		0.008

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2		0.70	<del>57</del> 0	0.028
e1	2.1	10	0.0	083
11	=0.	0.90	<del>77</del> .%	0.035

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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